

MAY 24-27, 2026
International Convention Center
SHANGHAI CHINA

First Call For Papers

October 12 2025 Papers Submission

January 19 2026 Author Notification

February 09 2026 Final Submission

CALL FOR PAPERS

The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world's premier forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS 2026 will be held in Shanghai, China, from May 24 to 27, 2026. ISCAS 2026 is driven by the theme "Circuits and Systems for Intelligent Society", catalyzing transformative innovation at the intersection of circuits, systems, and Artificial Intelligence to foster the development of a smart and sustainable society.

This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demonstrations and workshops on emerging topics, covering various topics in circuits and systems.

Collecting contributions in areas of Circuits and Systems, including but not limited to:

- » Analog and Mixed Signal Circuits and Systems
- » Digital Integrated Circuits and System
- » Power and Energy Circuits and Systems
- » Sensory Circuits and Systems
- » Nonlinear Systems and Circuit Theory
- » Digital Signal Processing
- » Multimedia Systems and Applications
- » Communications Circuits and Systems
- » Biomedical Circuits and Systems
- » Neural Networks and Neuromorphic Engineering
- » High-performance Computing for AI
- » Circuits and Systems for Quantum Computing
- » Beyond CMOS: Nanoelectronics and Heterogeneous
- » Education in Circuits and Systems

Paper Submission

Selected papers will be invited for possible publication in the IEEE Transactions on Circuits and Systems I: Regular Papers, IEEE Transactions on Circuits and Systems II: Express Briefs, IEEE Transactions on Biomedical Circuits and Systems, IEEE Open Journal of Circuits and Systems, or IEEE Transactions on Circuits and Systems for Artificial Intelligence.



2026.ieee-iscas.org

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